

Effect of silica on thermal stability of Poly(amide-imide) for Electronic Material

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Poly(amide-imide) was synthesized at low temperature process to offer a thermally stable membrane for electronic material. The high thermal stability with high glass transition temperature could be used to various applications such as semiconductors, integrated circuits, coating materials and display. Thermal stabilities of the polymer was confirmed by thermogravimetric analysis (TGA) and differential scanning calorimetry (DSC).